

Atty. Docket No. **YOR920050126US1**

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1. Name of conveying party(ies): Howard H. Chen Louis L. Hsu Jack A. Mandelman	2. Name and address of receiving party(ies): Name: International Business Machines Corporation Address: New Orchard Road Armonk, NY 10504
Additional name(s) of conveying party(ies) attached? ___ Yes <u>X</u> No	Additional name(s) & addresses attached? ___ Yes <u>X</u> No
3. Nature of conveyance: <u>X</u> Assignment	4. Patent Application number(s) 11/218198
Execution Date(s): <u>August 31, 2005,</u> <u>August 19, 2005, August 19, 2005</u>	Execution Date(s): <u>August 31, 2005,</u> <u>August 19, 2005, August 19, 2005</u>
5. Name and address of party to whom correspondence concerning document should be mailed: Name: Satheesh K. Karra Address: IBM Corporation Intellectual Property Law Dept. P.O. Box 218 Yorktown Heights, NY 10598	6. Total number of applications involved: 1
	7. Total fee (37 CFR 3.41): \$40.00 <u>X</u> Charge to Deposit Account No.: <u>09-0468</u>
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8. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of original document. Satheesh K. Karra (Reg. No. 40,246) <u>K. Satheesh</u> <u>October 17, 2005</u> Name of Person Signing Signature Date Total Number of pages including cover sheet, attachments, and document: <u>5</u>	

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PATENT

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~~REEL: 016897 FRAME: 0193~~

CH \$40.00 090468 11218198

(JOINT FORM)

(IBM Docket) YOR920050126US1

Assignment

Whereas, we

INVENTOR
AND CITY

(1) Howard H. Chen
County of Westchester

of Yorktown Heights
and State of New York

INVENTOR
AND CITY

(2) Louis L. Hsu
County of Dutchess

of Fishkill
and State of New York

INVENTOR
AND CITY

(3) Jack A. Mandelman
County of Henderson

of Flat Rock
and State of North Carolina

have invented certain improvements in

TITLE

METHOD TO INTEGRATE AND FABRICATE COPLANAR
DIELECTRICALLY-ISOLATED REGIONS OF DIFFERENT
SEMICONDUCTOR MATERIALS ON A SUBSTRATE

DATES THAT
INVENTORS
SIGNED THE
DECLARATION

and executed, respectively, a United States patent application therefor on

(1) 8/31 2005, and (2) 8/19 2005,
(3) 2005,

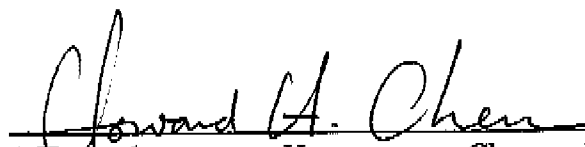
Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said applications to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

Signed and sealed

CITY AND
DATE

(1) at Yorktown
on August 31, 2005,

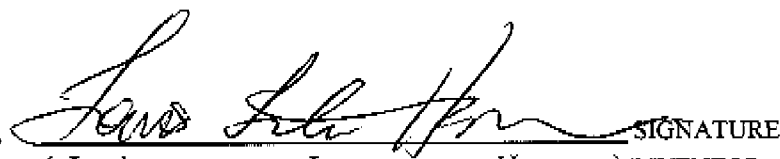

(Howard H. Chen) SIGNATURE
FIRST NAME MIDDLE INITIAL LAST NAME INVENTOR

(JOINT FORM)

(IBM Docket) YOR920050126US1

CITY AND
DATE(2) at
onHopewell, NJ
Aug. 19

2005,



SIGNATURE

(Louis
FIRST NAMEL.
MIDDLE INITIALHsu) INVENTOR
LAST NAMECITY AND
DATE(3) at
on

2005,

(Jack A. Mandelman) INVENTOR
FIRST NAME MIDDLE INITIAL LAST NAME

SIGNATURE

(JOINT FORM)

(IBM Docket) YOR920050126US1

Assignment

Whereas, we

INVENTOR
AND CITY(1) Howard H. Chen
County of Westchesterof Yorktown Heights
and State of New YorkINVENTOR
AND CITY(2) Louis L. Hsu
County of Dutchessof Fishkill
and State of New YorkINVENTOR
AND CITY(3) Jack A. Mandelman
County of Hendersonof Flat Rock
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TITLE

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DIELECTRICALLY-ISOLATED REGIONS OF DIFFERENT
SEMICONDUCTOR MATERIALS ON A SUBSTRATE

DATES THAT

and executed, respectively, a United States patent application therefor on

INVENTORS

(1) 2005, and (2) 2005,
(3) 19 AUGUST 2005,

SIGNED THE

DECLARATION

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said applications to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

Signed and sealed

CITY AND
DATE(1) at
on

2005,

SIGNATURE

(Howard H. Chen) INVENTOR
FIRST NAME MIDDLE INITIAL LAST NAME

PATENT

REEL: 016897 FRAME: 0196

(JOINT FORM)

(IBM Docket) YOR920050126US1

CITY AND (2) at
DATE on 2005, _____ SIGNATURE
(Louis L. Hsu) INVENTOR
FIRST NAME MIDDLE INITIAL LAST NAME

CITY AND (3) at FLAT ROCK, NC
DATE on 19 AUGUST 2005, Jack A. Mandelman SIGNATURE
(Jack A. Mandelman) INVENTOR
FIRST NAME MIDDLE INITIAL LAST NAME